

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5602026

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	06/24/2019
RECEIVING PARTY DATA	
Name:	EPISTAR CORPORATION
Street Address:	21 LI-HSIN RD.
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300 R.O.C.
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	7261454
CORRESPONDENCE DATA	
Fax Number:	(713)623-4846
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7136234844
Email:	tjeffrey@pattersonsheridan.com, psdocketing@pattersonsheridan.com
Correspondent Name:	PATTERSON & SHERIDAN, LLP
Address Line 1:	595 SHREWSBURY AVENUE
Address Line 2:	SUITE 100
Address Line 4:	SHREWSBURY, NEW JERSEY 07702
ATTORNEY DOCKET NUMBER:	EPIS/0001-TSMC TO EPIS
NAME OF SUBMITTER:	KEITH TABOADA
SIGNATURE:	/Keith Taboada/
DATE SIGNED:	07/02/2019
Total Attachments: 1	
source=TSMC_EPIS_Assignment#page1.tif	

ASSIGNMENT

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. (hereinafter "ASSIGNOR"), of No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is the owner in the United States Patent and Trademark Office of the full and exclusive right, title and interest in and to the U.S. Patent No. 7,261,454 filed on September 23, 2005.

WHEREAS, Epistar Corporation, (hereinafter "ASSIGNEE"), of 21, Li-Hsin Rd., Science-based Industrial Park, Hsinchu 300, TAIWAN, R.O.C., is desirous of acquiring the entire right, title, and interest in, and to said patent application, said invention and any patents that may issue on said application within the United States of America and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, ASSIGNOR have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and ASSIGNOR hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND ASSIGNOR HEREBY covenant that ASSIGNOR have full right to convey the entire interest herein assigned, and that ASSIGNOR have not executed, and will not execute, any agreement in conflict herewith.

AND ASSIGNOR HEREBY further covenant and agree that ASSIGNOR will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

TAIWAN SEMICONDUCTOR
MANUFACTURING COMPANY, LTD.


Signature

Billie Chen
Printed Name

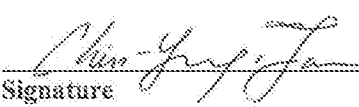
Associate General Counsel and Chief IP Counsel

Title

Date

June 24, 2019

EPISTAR CORPORATION


Signature

Fan, Chin-Yung
Printed Name

President

Title

Date

July 1, 2019

